

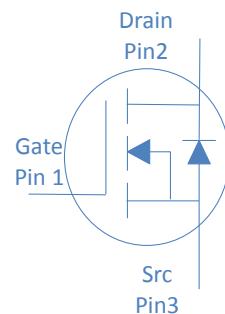
**45V N-Ch Power MOSFET**
**Feature**

- ◊ Optimized for high speed switching, Logic Level
- ◊ Enhanced Body diode dv/dt capability
- ◊ Enhanced Avalanche Ruggedness
- ◊ 100% UIS Tested, 100% Rg Tested
- ◊ Lead Free, Halogen Free

$V_{DS}$	45	V	
$R_{DS(on),typ}$	$V_{GS}=10V$	2.5	$m\Omega$
$R_{DS(on),typ}$	$V_{GS}=4.5V$	3.2	$m\Omega$
$I_D$ (Silicon Limited)	186	A	
$I_D$ (Package Limited)	120	A	

**Application**

- ◊ Synchronous Rectification in SMPS
- ◊ Hard Switching and High Speed Circuit
- ◊ Power Tools
- ◊ UPS
- ◊ Motor Control

**TO-220**


Part Number	Package	Marking
HGP029NE4SL	TO-220	GP029NE4SL

**Absolute Maximum Ratings at  $T_j=25^\circ C$  (unless otherwise specified)**

Parameter	Symbol	Conditions	Value	Unit
Continuous Drain Current (Silicon Limited)	$I_D$	$T_C=25^\circ C$	186	A
Continuous Drain Current (Package Limited)		$T_C=100^\circ C$	132	
Continuous Drain Current (Package Limited)		$T_C=25^\circ C$	120	
Drain to Source Voltage	$V_{DS}$	-	45	V
Gate to Source Voltage	$V_{GS}$	-	$\pm 20$	V
Pulsed Drain Current	$I_{DM}$	-	450	A
Avalanche Energy, Single Pulse	$E_{AS}$	$L=0.1mH, T_C=25^\circ C$	180	mJ
Power Dissipation	$P_D$	$T_C=25^\circ C$	176	W
Operating and Storage Temperature	$T_J, T_{stg}$	-	-55 to 175	°C

**Absolute Maximum Ratings**

Parameter	Symbol	Max	Unit
Thermal Resistance Junction-Case	$R_{\theta JC}$	0.85	°C/W
Thermal Resistance Junction-Ambient	$R_{\theta JA}$	46	°C/W

**Electrical Characteristics at  $T_j=25^\circ\text{C}$  (unless otherwise specified)**
**Static Characteristics**

Parameter	Symbol	Conditions	Value			Unit	
			min	typ	max		
Drain to Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}}=0\text{V}, I_D=250\mu\text{A}$	45	-	-	V	
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{GS}}=V_{\text{DS}}, I_D=250\mu\text{A}$	1	1.4	2		
Zero Gate Voltage Drain Current	$I_{\text{DSS}}$	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=45\text{V}, T_j=25^\circ\text{C}$	-	-	1	$\mu\text{A}$	
		$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=45\text{V}, T_j=100^\circ\text{C}$	-	-	100		
Gate to Source Leakage Current	$I_{\text{GSS}}$	$V_{\text{GS}}=\pm20\text{V}, V_{\text{DS}}=0\text{V}$	-	-	$\pm100$	nA	
Drain to Source on Resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}}=10\text{V}, I_D=20\text{A}$	TO-220	-	2.5	2.9	m $\Omega$
		$V_{\text{GS}}=4.5\text{V}, I_D=20\text{A}$	TO-220	-	3.2	4.0	m $\Omega$
Transconductance	$g_{\text{fs}}$	$V_{\text{DS}}=5\text{V}, I_D=20\text{A}$	-	TBD	-	S	
Gate Resistance	$R_G$	$V_{\text{GS}}=0\text{V}, V_{\text{DS}} \text{ Open}, f=1\text{MHz}$	-	1.6	-	$\Omega$	

**Dynamic Characteristics**

Input Capacitance	$C_{\text{iss}}$	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=20\text{V}, f=1\text{MHz}$	-	3322	-	pF
Output Capacitance	$C_{\text{oss}}$		-	1367	-	
Reverse Transfer Capacitance	$C_{\text{rss}}$		-	96	-	
Total Gate Charge (10V)	$Q_g (10\text{V})$	$V_{\text{DD}}=20\text{V}, I_D=20\text{A}, V_{\text{GS}}=10\text{V}$	-	50	-	nC
Total Gate Charge (4.5V)	$Q_g (4.5\text{V})$		-	25	-	
Gate to Source Charge	$Q_{\text{gs}}$		-	8	-	
Gate to Drain (Miller) Charge	$Q_{\text{gd}}$		-	10	-	
Turn on Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}}=20\text{V}, I_D=20\text{A}, V_{\text{GS}}=10\text{V}$ , $R_G=10\Omega$ ,	-	14	-	ns
Rise time	$t_r$		-	12	-	
Turn off Delay Time	$t_{\text{d}(\text{off})}$		-	57	-	
Fall Time	$t_f$		-	18	-	

**Reverse Diode Characteristics**

Diode Forward Voltage	$V_{\text{SD}}$	$V_{\text{GS}}=0\text{V}, I_F=20\text{A}$	-	0.9	1.2	V
Reverse Recovery Time	$t_{\text{rr}}$	$V_R=20\text{V}, I_F=20\text{A}, dI_F/dt=200\text{A}/\mu\text{s}$	-	40	-	ns
Reverse Recovery Charge	$Q_{\text{rr}}$		-	64	-	nC